

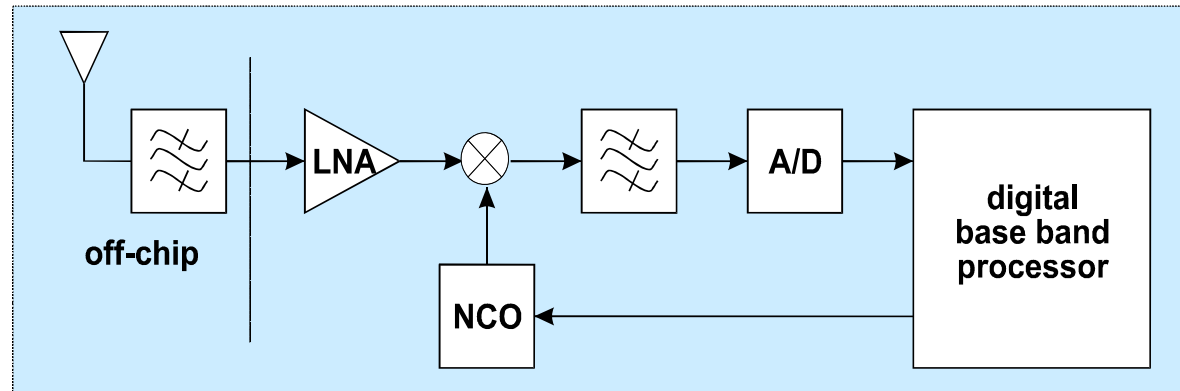
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# Coupled Interference in Mixed Signal Wireless ICs and Implications for Package Design

*Robert C. Frye*

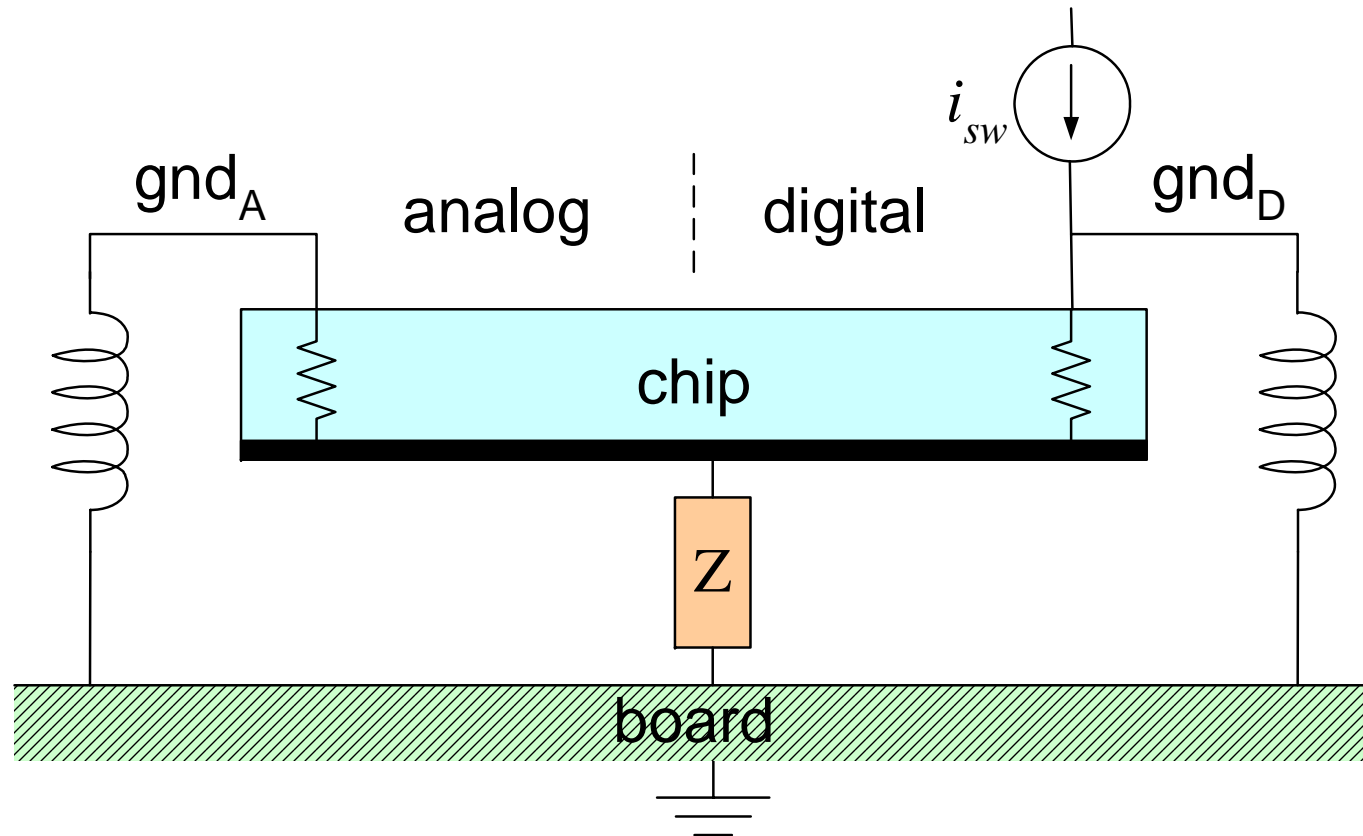
Agere Systems  
700 Mountain Avenue, Murray Hill, NJ

## “Mainly digital” receivers



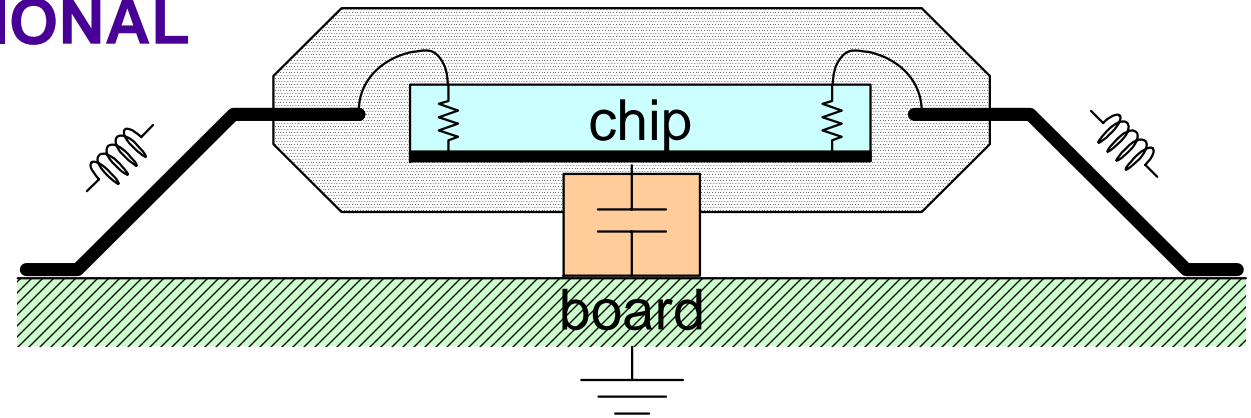
- Direct conversion or low-IF architecture eliminates analog IF stages.
- Digital implementation exploits Moore's Law.
- Mixed-signal IC design leads to crosstalk noise problems.

## Switching transient coupling

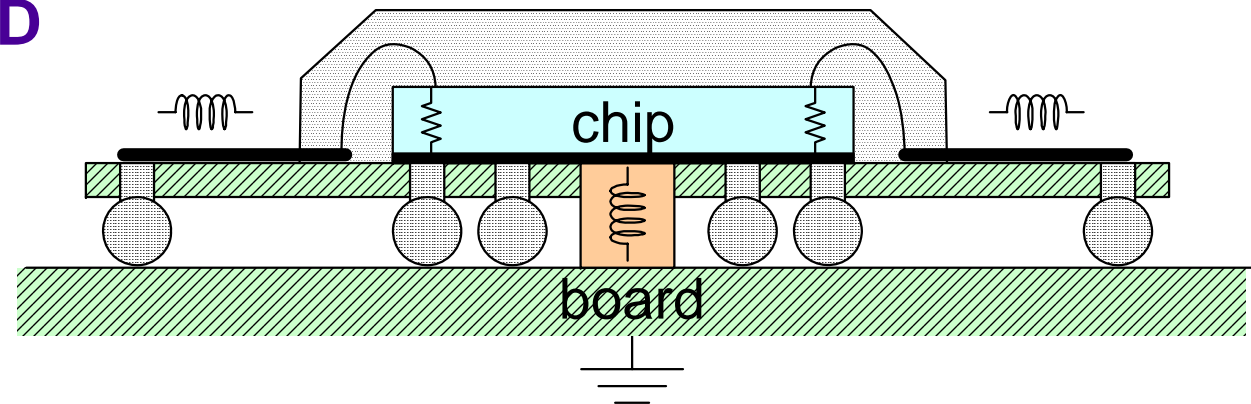


## Example package type comparisons

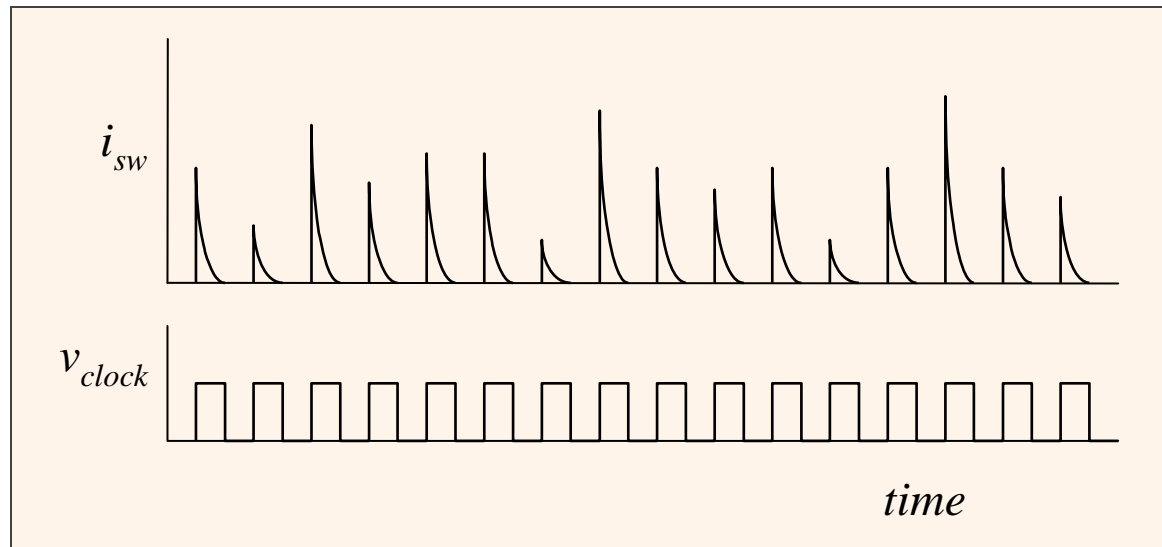
### CONVENTIONAL



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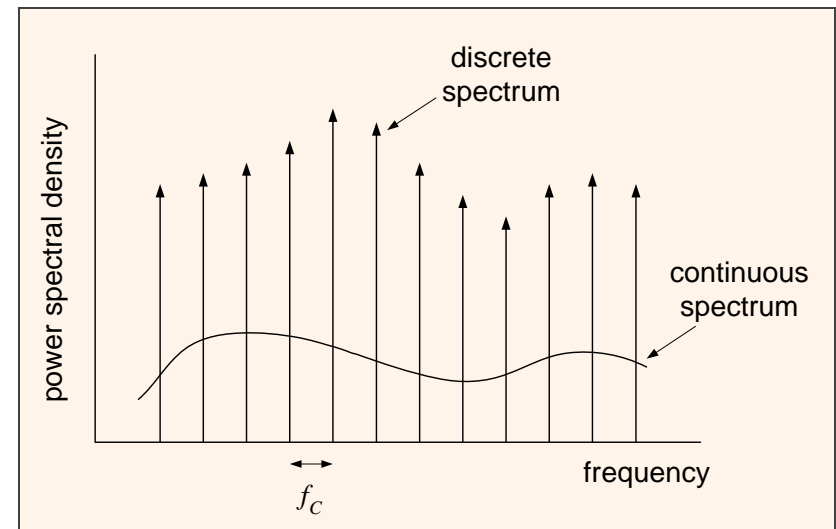
## Switching transients



- Digital switching current transients appear stochastic in nature, but are correlated with the digital clock.
- This is a property of a cyclostationary process.

## Spectral properties of cyclostationary waveforms

- Spectrum has both discrete and continuous components.
- Continuous spectrum depends on cycle-to-cycle correlation.
- Discrete spectrum, at multiples of clock frequency, depends on time-averaged waveform.



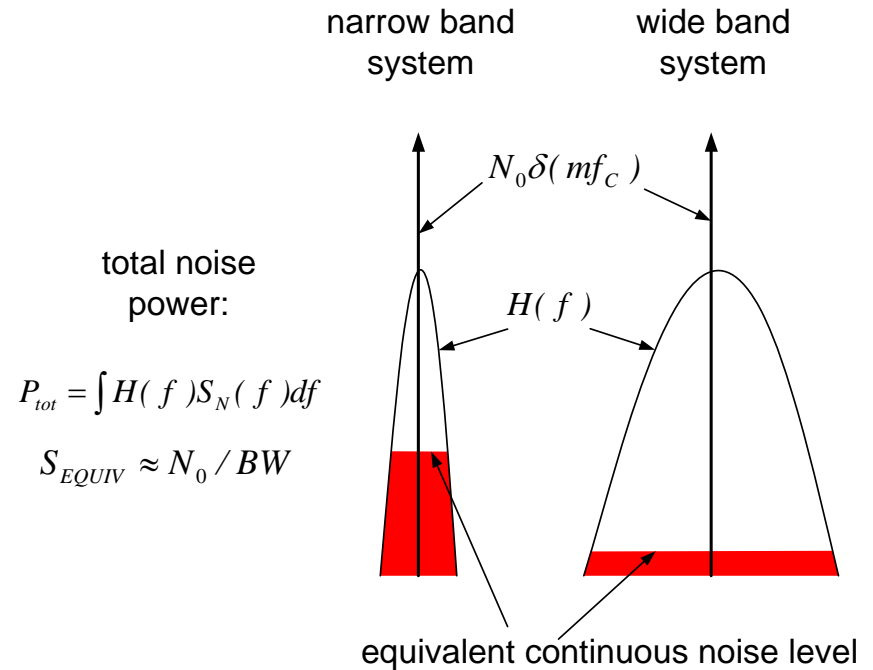
## Coupled digital noise in wireless systems

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- The discrete spectral component of a cyclostationary noise source is particularly important because its power is concentrated at specific frequencies.
- For common digital clock frequencies, many spectral lines will fall inside a communication band, so interference is unavoidable.
- The severity of the interference depends not only on the degree of coupling, but also on the receiver's resolution bandwidth.

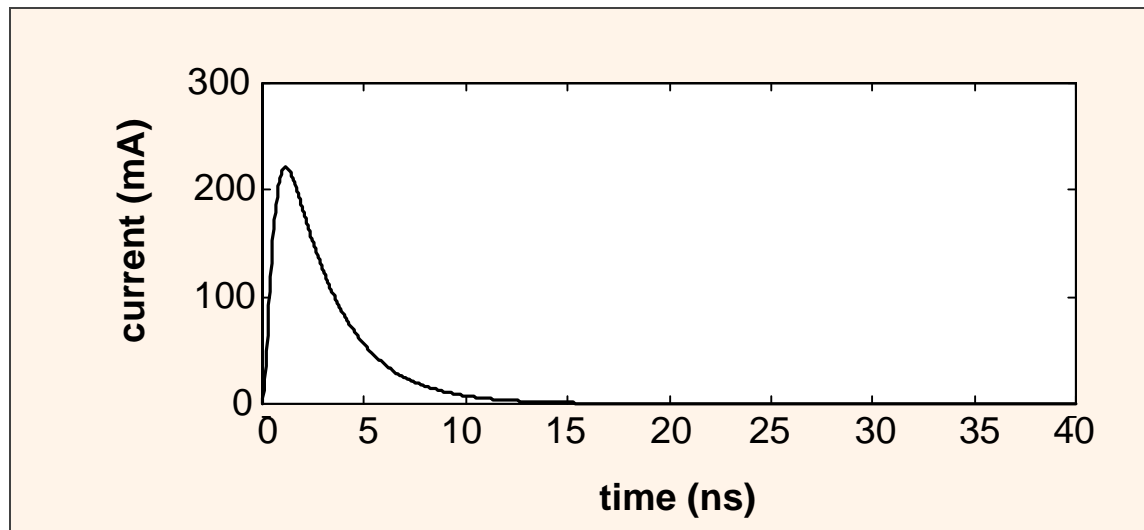
# Discrete spectral noise and system bandwidth

- Discrete spectral noise is a delta function with infinite density at a single frequency.
- We can define an equivalent continuous spectrum of noise such that total noise power is the same.
- Discrete noise has greater impact on narrow band systems.





# Average switching current macromodel for discrete spectrum



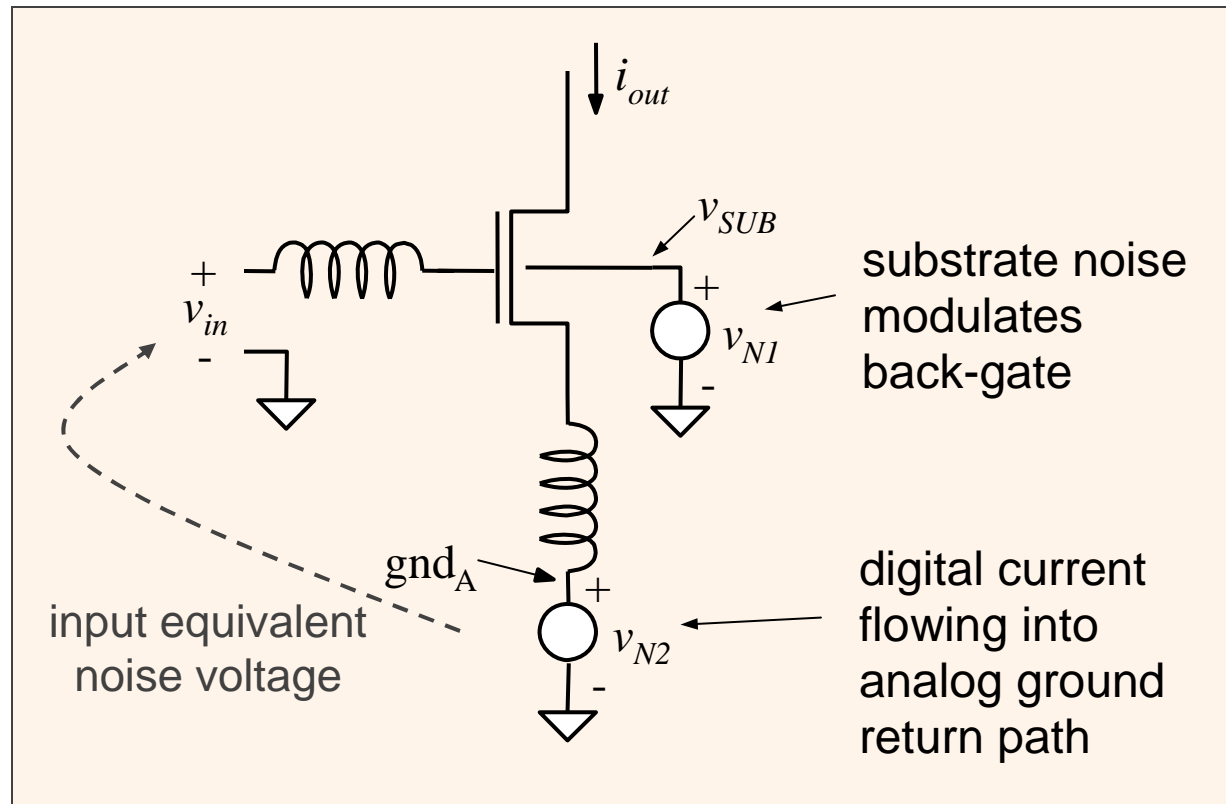
## Example assumptions:

$$\text{dc power : } I_{DC} = \langle I(t) \rangle = 20mA$$

$$\text{rise time : } t_{rise} = 1ns$$

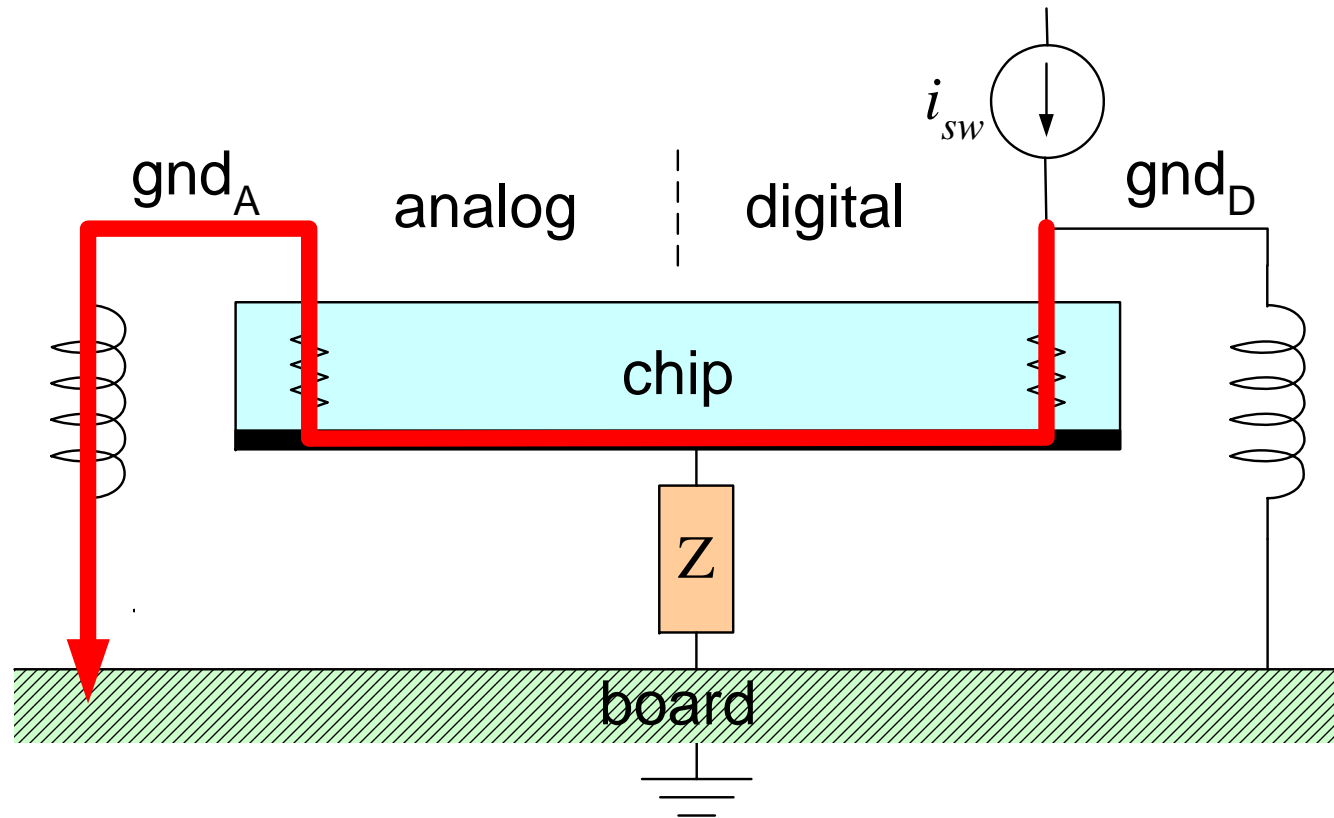
$$\text{pulse width : } \delta t = \langle t \cdot I(t) \rangle / \langle I(t) \rangle = 5ns$$

# Noise coupling mechanisms



typical LNA input stage

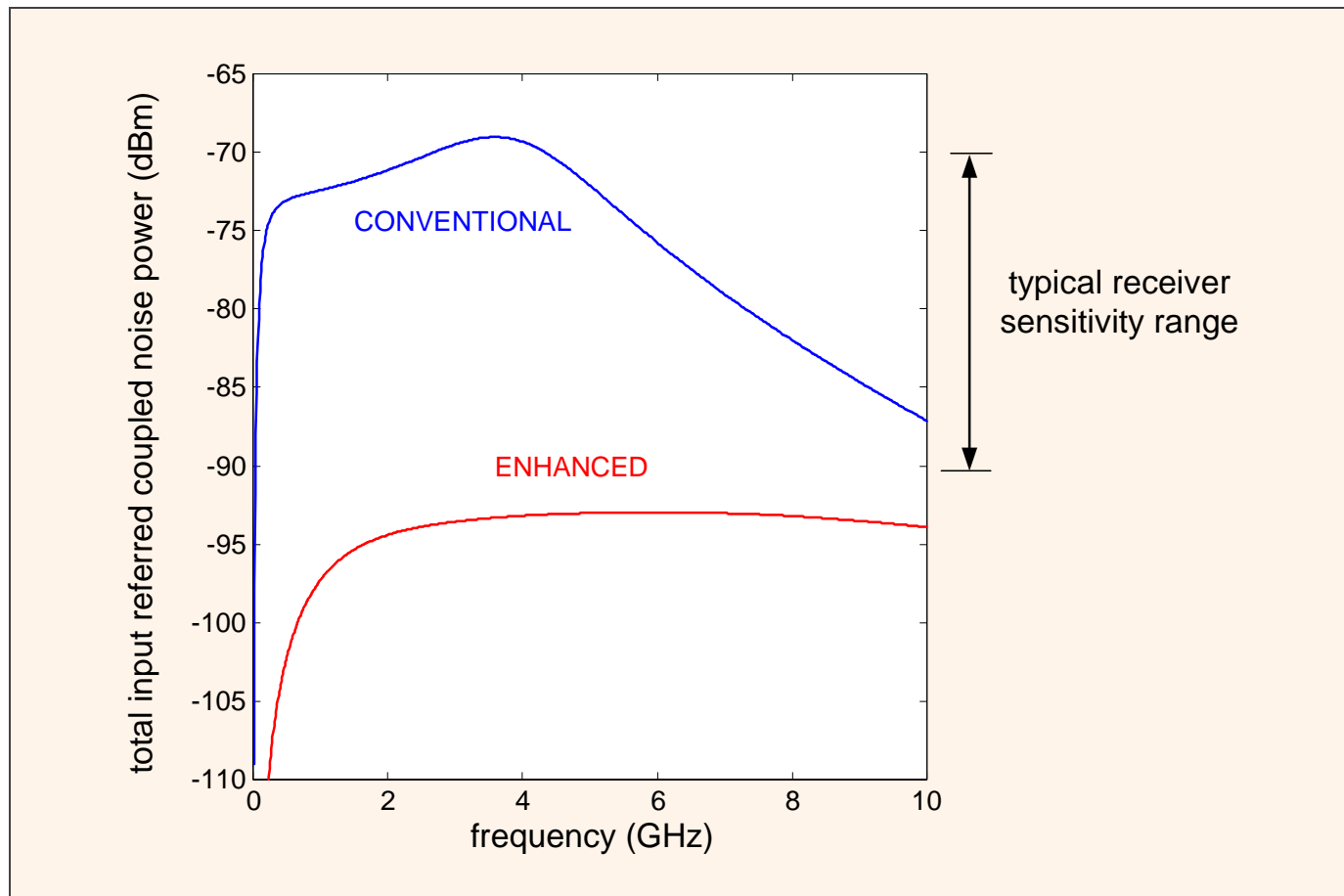
## Key noise coupling mechanism



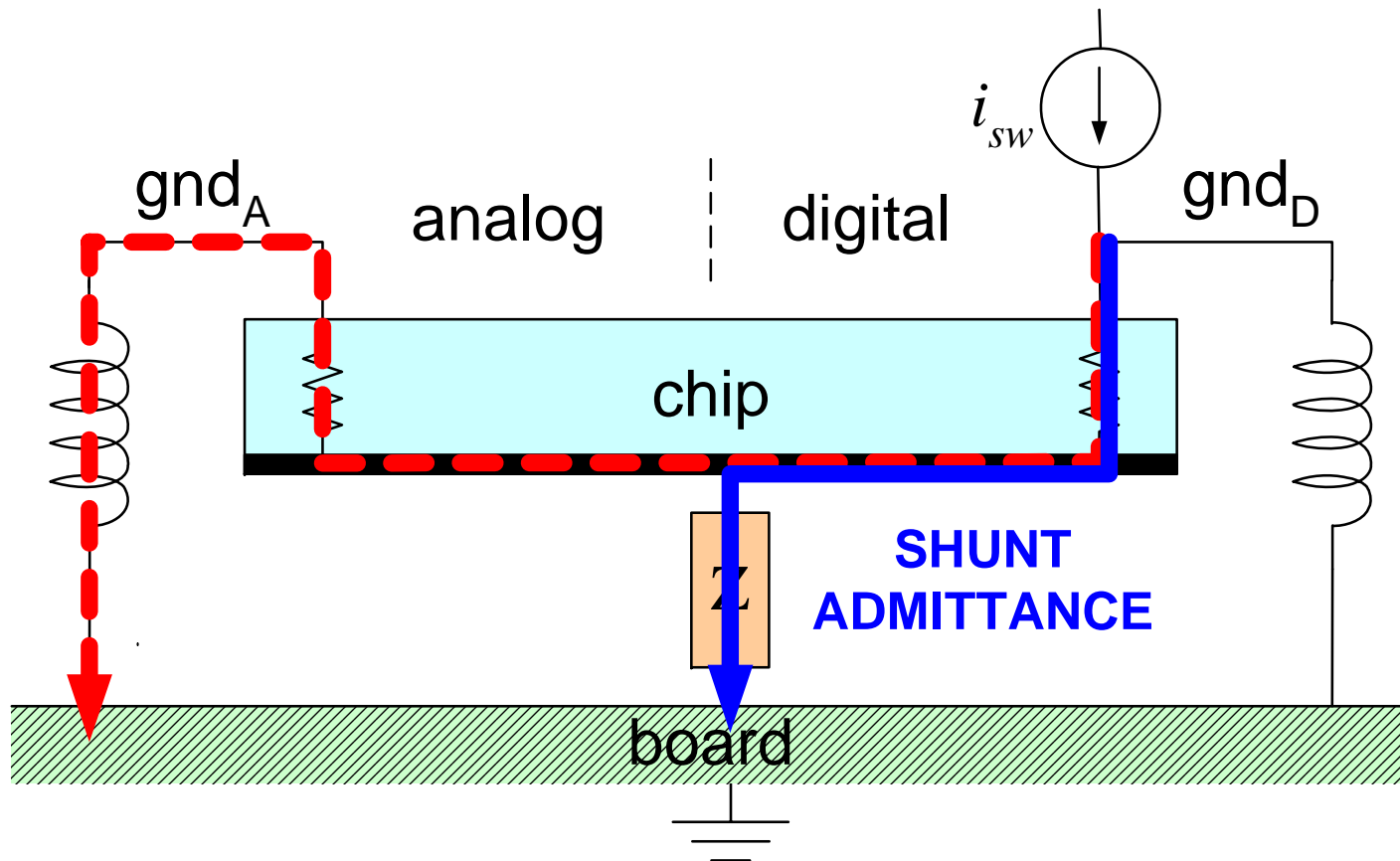
## Package assumptions

parameter	value	description
$L_P$	3 nH	Package pin inductance
$L_{GD}$	0.6 nH	Ground inductance (5 pins)
$L_{GA}$	0.6 nH	Ground inductance (5 pins)
$C_{BG}$	3.5 pF	Substrate to ground capacitance (conventional package)
$L_{BG}$	0.05 nH	Substrate to ground inductance (enhanced package)

## Typical coupled noise power comparison

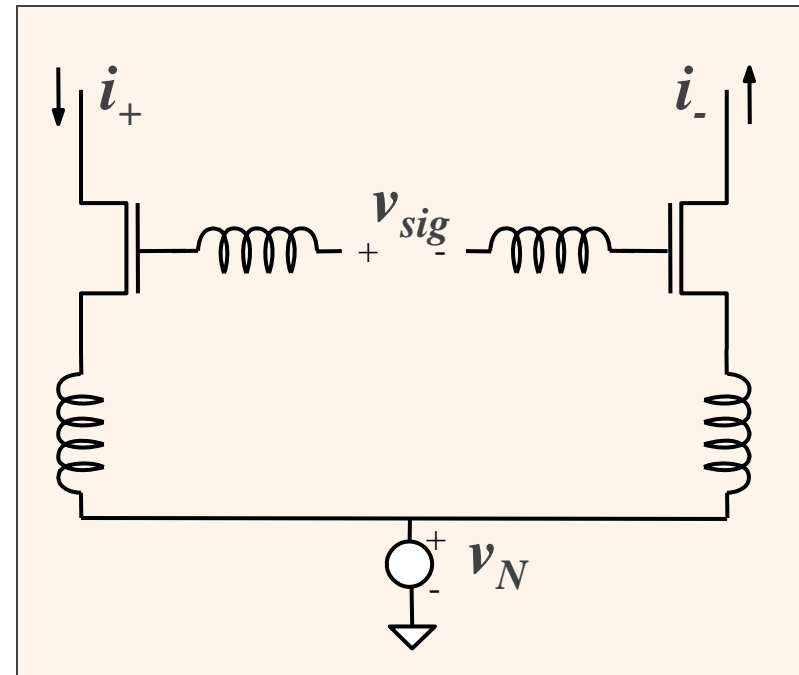


## Noise reduction mechanism



## Differential noise cancellation

- Coupled switching noise is not really noise, but crosstalk.
- It can be partially eliminated by the use of differential-mode circuit designs.
- The effectiveness of this is limited by component matching.



**Differential LNA**

## Circuit and system design issues

- Coupled noise levels need to be substantially below sensitivity to meet SNR requirements.
- Enhanced packages with low substrate ground impedance reduce coupled noise by 20-25 dB.
- This greatly relaxes the component matching requirements for semiconductor technology.



## Package design implications

- The main source of coupled noise at wireless frequencies is by leakage of digital switching current into the analog ground return path.
- The IC substrate is the common impedance path for this coupling.
- Low pin inductance (usually resulting from miniaturization) improves noise performance.
- Enhanced packages that provide low impedance substrate ground can substantially reduce noise compared with conventional leaded packages.